

INTRODUCE:

HVGT high voltage silicon rectifier assembly is made of high quality silicon wafer chip and high reliability epoxy resin sealing structure, and through professional testing equipment inspection qualified after to customers.

FEATURES:

1. High reliability design.
2. High voltage design.
3. High current . low forward voltage
4. Conform to RoHS and SGS.
5. Epoxy resin molded in vacuumHave anticorrosion in the surface.

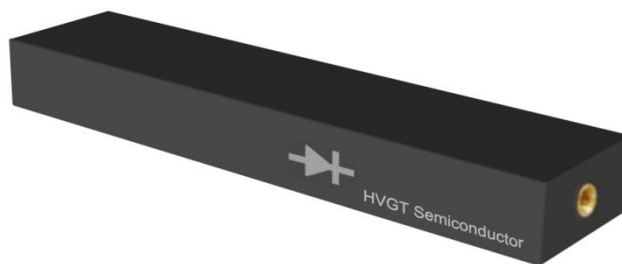
APPLICATIONS:

1. Accelerator power supply.
2. High voltage test equipment circuit .
3. General purpose high voltage rectifier.
4. Environmental desulfurization system.

MECHANICAL DATA:

1. Case: epoxy resin molding.
2. Terminal: screw holes.
3. Net weight: 125grams (approx).

SHAPE DISPLAY:

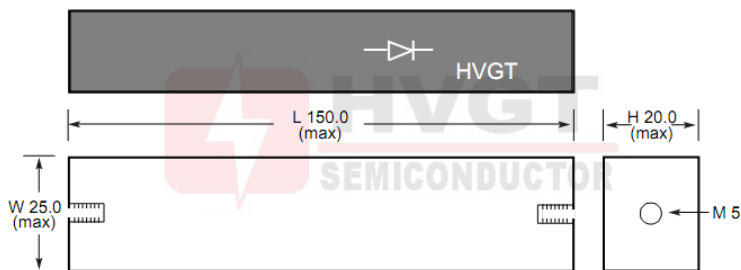


SIZE: (Unit:mm)

HVGT NAME: HVC-152520

HVC-152520 Series

Screw Holes M5



Unit:mm

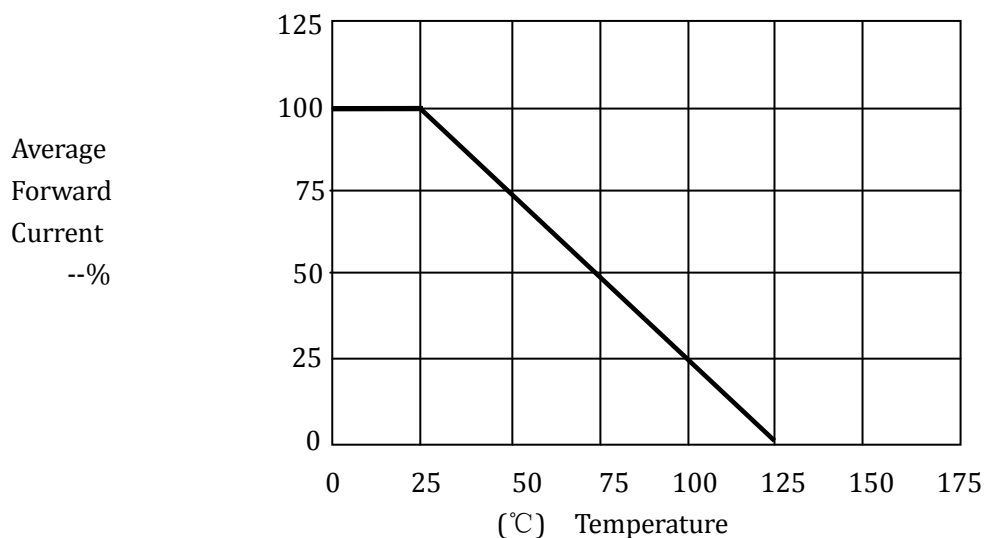
MAXIMUM RATINGS AND CHARACTERISTICS: (Absolute Maximum Ratings)

Items	Symbols	Condition	Data Value	Units
Repetitive Peak Reverse Voltage	V_{RRM}	$T_A=25^{\circ}C$	30	kV
Non-Repetitive Peak Reverse Voltage	V_{RSM}	$T_A=25^{\circ}C$	36	kV
Average Forward Current Maximum	I_{FAVM}	$T_A=25^{\circ}C$	3.0	A
		$T_{OIL}=55^{\circ}C$	3.0	A
Non-Repetitive Forward Surge Current	I_{FSM}	$T_A=25^{\circ}C$; 50Hz Half-Sine Wave; 8.3ms	60	A
Junction Temperature	T_J		125	$^{\circ}C$
Allowable Operation Case Temperature	T_C		-40~+125	$^{\circ}C$
Storage Temperature	T_{STG}		-40~+150	$^{\circ}C$

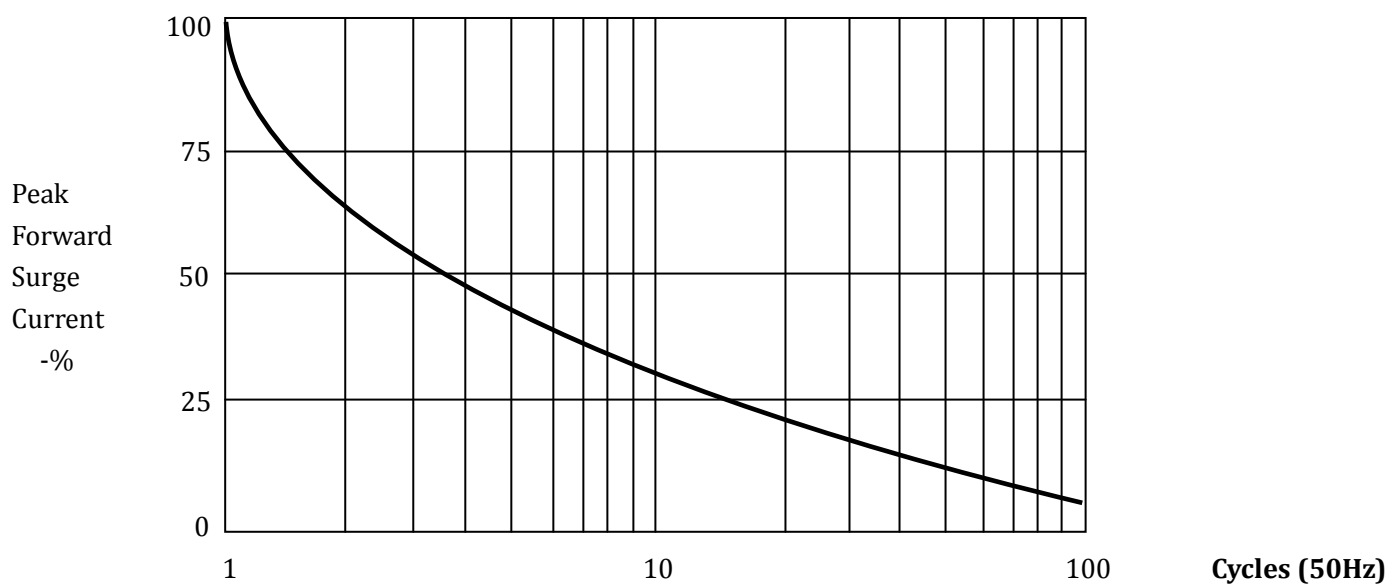
ELECTRICAL CHARACTERISTICS: $T_A=25^{\circ}C$ (Unless Otherwise Specified)

Items	Symbols	Condition	Data value	Units
Maximum Forward Voltage Drop	V_{FM}	at $25^{\circ}C$; at I_{FAVM}	33	V
Maximum Reverse Current	I_{R1}	at $25^{\circ}C$; at V_{RRM}	5.0	μA
	I_{R2}	at $100^{\circ}C$; at V_{RRM}	50	μA
Maximum Reverse Recovery Time	T_{RR}	at $25^{\circ}C$; $I_F=0.5I_R$; $I_R=I_{FAVM}$; $I_{RR}=0.25I_R$	--	nS
Junction Capacitance	C_J	at $25^{\circ}C$; $V_R=0V$; $f=1MHz$	--	pF

Forward Current Derating Curve



Non-Repetitive Surge Current



MARKING:

Type	Code	Cathode Mark
AW030S300D	AW030S300D HVGT	

PART NUMBER NOTE:

Type	Chip	I _{F(AV)}	Connecting end	V _{RRM}	T _{RR}
A	W	030	S	300	D
Assembly Series	Wafer Chip	3.0A	L=Lead S=Screw Holes	30kV	(U)75ns (G)100ns (D) Standard Recovery Time